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PATENT Atty. Dkt. No. AMAT/4258/CPI/COPPER/PJS

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Yezdi Dordi

Serial No.: 09/586,736

Confirmation No.: 7891

Filed:

June 5, 2000

For: PROGRAMMABLE ANODE

APPARATUS AND ASSOCIATED METHOD

Assistant Commissioner for Patents

Dear Sir:

Group Art Unit: 1741

Examiner: ...

Leader, W.

CERTIFICATE OF MAILING 37 CFR 1,8

rist taass Mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231

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RESPONSE TO RESTRICTION REQUIREMENT DATED OCTOBER 2, 2001

In response to the Restriction Requirement dated October 2, 2001, having a shortened statutory period for response set to expire on November 2, 2001, please aims pending in the application.

APR 2 3 2002

APR 2 3 2002 enter the following amendments and reconsider the claims pending in the application for resenns discussed helow.

IN THE SPECIFICATION:

Please replace the paragraph at page 2, lines 3-13, with the following paragraph:

Deposition of a metal in electroplating is accomplished by providing an electric current to the seed layer and then exposing the seed layer to an electrolytic solution containing the metal to be deposited. One embodiment of an electroplating system that performs such metal deposition is depicted in FIG. 1. The device, known as a fountain plater 10, deposits metal on the seed layer 15 of a substrate 48. The fountain plater 10 includes an electrolyte cell 12 having a removable substrate support 14, and an anode 16 mounted to the electrolyte cell 12. A positive electrical pole 45 of the controller 42 is

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